

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	Heat Sink Riveted to Memory Module with Upper Slots and Open Bottom Edge for Air Flow
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Application Number :

Confirmation Number:

First Named Applicant: Ren-Kang Chiou

Attorney Docket Number: ML-16

Art Unit:

Examiner:

Search string: (6535387 or 6473306 or 6449156 or 6424532 or 6362966 or 5543660).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6535387	2003-05-18	Summers , et al.	B1	361	704
	2	6473306	2002-10-29	Koseki , et al.	B1	361	704
	3	6449156	2002-09-10	Han , et al.	B1	361	704
	4	6424532	2002-07-23	Kawamura	B1	361	708
	5	6362966	2002-03-26	Ali , et al.	B1	361	728
	6	5543660	1996-08-06	Dombroski	B1	257	707

Signature

Examiner Name	Date